MBR150, MBR160

MBR160 is a Preferred Device

Axial Lead Rectifiers

The MBR150/160 series employs the Schottky Barrier principle in a large area metal-to-silicon power diode. State-of-the-art geometry features epitaxial construction with oxide passivation and metal overlap contact. Ideally suited for use as rectifiers in low-voltage, high-frequency inverters, free wheeling diodes, and polarity protection diodes.

Features

- Low Reverse Current
- Low Stored Charge, Majority Carrier Conduction
- Low Power Loss/High Efficiency
- Highly Stable Oxide Passivated Junction
- These devices are manufactured with a Pb–Free external lead finish only*

Mechanical Characteristics

- Case: Epoxy, Molded
- Weight: 0.4 gram (approximately)
- Finish: All External Surfaces Corrosion Resistant and Terminal Leads are Readily Solderable
- Lead and Mounting Surface Temperature for Soldering Purposes: 220°C Max. for 10 Seconds, 1/16" from case
- Shipped in Plastic Bags, 1000 per bag
- Available Tape and Reeled, 5000 per reel, by adding a "RL" suffix to the part number
- Polarity: Cathode Indicated by Polarity Band



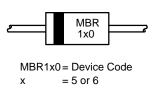
ON Semiconductor®

http://onsemi.com

SCHOTTKY BARRIER RECTIFIERS 1.0 AMPERE 50, 60 VOLTS



MARKING DIAGRAM



ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

Preferred devices are recommended choices for future use and best overall value.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MBR150, MBR160

MAXIMUM RATINGS

Rating	Symbol	MBR150	MBR160	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	50	60	V
RMS Reverse Voltage	V _{R(RMS)}	35	42	V
Average Rectified Forward Current (Note 1) $(V_{R(equiv)} \le 0.2 V_{R}(dc), T_{L} = 90^{\circ}C, R_{\theta JA} = 80^{\circ}C/W, P.C.$ Board Mounting, $T_{A} = 55^{\circ}C)$	Io	1	.0	А
Nonrepetitive Peak Surge Current (Surge applied at rated load conditions, halfwave, single phase, 60 Hz, $T_L = 70^{\circ}C$)	I _{FSM} 25 (for one		ne cycle)	А
Operating and Storage Junction Temperature Range (Reverse Voltage Applied)	T _J , T _{stg}	- 65 to	o +150	°C
Peak Operating Junction Temperature (Forward Current Applied)	T _{J(pk)}	15	50	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS (Notes 1 and 2)

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient		80	°C/W

ELECTRICAL CHARACTERISTICS ($T_L = 25^{\circ}C$ unless otherwise noted) (Note 1)

Characteristic		Max	Unit
Maximum Instantaneous Forward Voltage (Note 2) $ \begin{aligned} &(i_F=0.1 \text{ A}) \\ &(i_F=1.0 \text{ A}) \\ &(i_F=3.0 \text{ A}) \end{aligned} $	VF	0.550 0.750 1.000	V
Maximum Instantaneous Reverse Current @ Rated dc Voltage (Note 2) $(T_L = 25^{\circ}C)$ $(T_L = 100^{\circ}C)$	i _R	0.5 5.0	mA

^{1.} Lead Temperature reference is cathode lead 1/32" from case.

ORDERING INFORMATION

Device	Package	Shipping [†]
MBR150	Axial Lead (Pb-Free)	1000 Units / Bag
MBR150RL	Axial Lead (Pb-Free)	5000 / Tape & Reel
MBR160	Axial Lead (Pb-Free)	1000 Units / Bag
MBR160RL	Axial Lead (Pb-Free)	5000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

^{2.} Pulse Test: Pulse Width = 300 μ s, Duty Cycle \leq 2.0%.

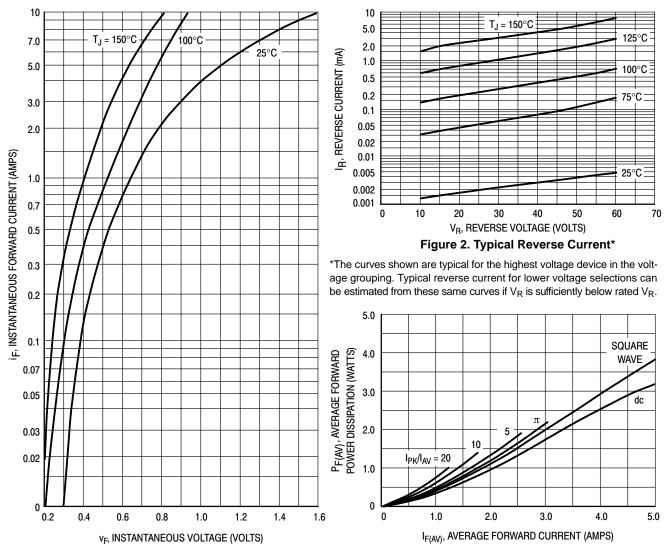


Figure 1. Typical Forward Voltage

Figure 3. Forward Power Dissipation

THERMAL CHARACTERISTICS

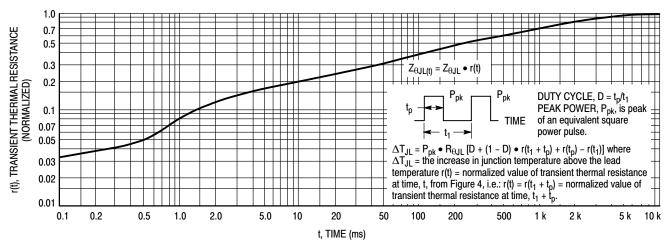


Figure 4. Thermal Response

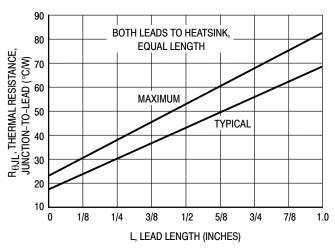


Figure 5. Steady-State Thermal Resistance

NOTE 1. — MOUNTING DATA:

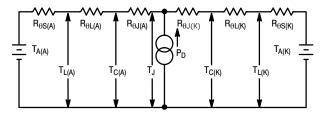
Data shown for thermal resistance junction—to—ambient $(R_{\theta JA})$ for the mounting shown is to be used as a typical guideline values for preliminary engineering or in case the tie point temperature cannot be measured.

Typical Values for $R_{\theta JA}$ in Still Air

Mounting	Lead Length, L (in)				В	
Method	1/8	1/4	1/2	3/4	$R_{ hetaJA}$	
1	52	65	72	85	°C/W	
2	67	80	87	100	°C/W	
3	_		50		°C/W	

NOTE 2. — THERMAL CIRCUIT MODEL:

(For heat conduction through the leads)



Use of the above model permits junction to lead thermal resistance for any mounting configuration to be found. For a given total lead length, lowest values occur when one side of the rectifier is brought as close as possible to the heatsink. Terms in the model signify:

 $T_A = Ambient Temperature$ $T_C = Case Temperature$

 $T_L = Lead Temperature$ $T_J = Junction Temperature$

 $R_{\theta S}$ = Thermal Resistance, Heatsink-to-Ambient

 $R_{\theta L}$ = Thermal Resistance, Lead-to-Heatsink

 $R_{\theta J}$ = Thermal Resistance, Junction–to–Case

P_D = Power Dissipation

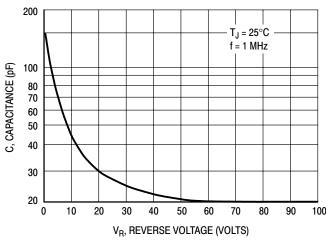
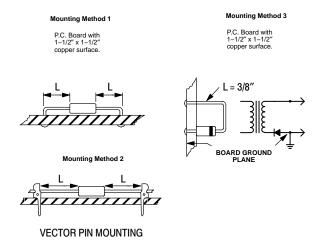


Figure 6. Typical Capacitance



(Subscripts A and K refer to anode and cathode sides, respectively.) Values for thermal resistance components are: $R_{\theta L} = 100 ^{\circ} \text{C/W/in typically and } 120 ^{\circ} \text{C/W/in maximum.}$ $R_{\theta J} = 36 ^{\circ} \text{C/W typically and } 46 ^{\circ} \text{C/W maximum.}$

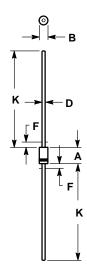
NOTE 3. — HIGH FREQUENCY OPERATION:

Since current flow in a Schottky rectifier is the result of majority carrier conduction, it is not subject to junction diode forward and reverse recovery transients due to minority carrier injection and stored charge. Satisfactory circuit analysis work may be performed by using a model consisting of an ideal diode in parallel with a variable capacitance. (See Figure 6)

Rectification efficiency measurements show that operation will be satisfactory up to several megahertz. For example, relative waveform rectification efficiency is approximately 70 percent at 2 MHz, e.g., the ratio of dc power to RMS power in the load is 0.28 at this frequency, whereas perfect rectification would yield 0.406 for sine wave inputs. However, in contrast to ordinary junction diodes, the loss in waveform efficiency is not indicative of power loss: it is simply a result of reverse current flow through the diode capacitance, which lowers the dc output voltage.

PACKAGE DIMENSIONS

AXIAL LEAD, DO-41 CASE 59-10 **ISSUE S**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: INCH.
 3. 59-04 OBSOLETE, NEW STANDARD 59-09.
 4. 59-03 OBSOLETE, NEW STANDARD 59-10.
 5. ALL RULES AND NOTES ASSOCIATED WITH JEDEC DO-41 OUTLINE SHALL APPLY
 6. POLARITY DENOTED BY CATHODE BAND.
 7. LEAD DIAMETER NOT CONTROLLED WITHIN F DIMENSION.

	INCHES		MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.161	0.205	4.10	5.20
В	0.079	0.106	2.00	2.70
D	0.028	0.034	0.71	0.86
F		0.050		1.27
K	1.000		25.40	

MBR150, MBR160

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free LISA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.